

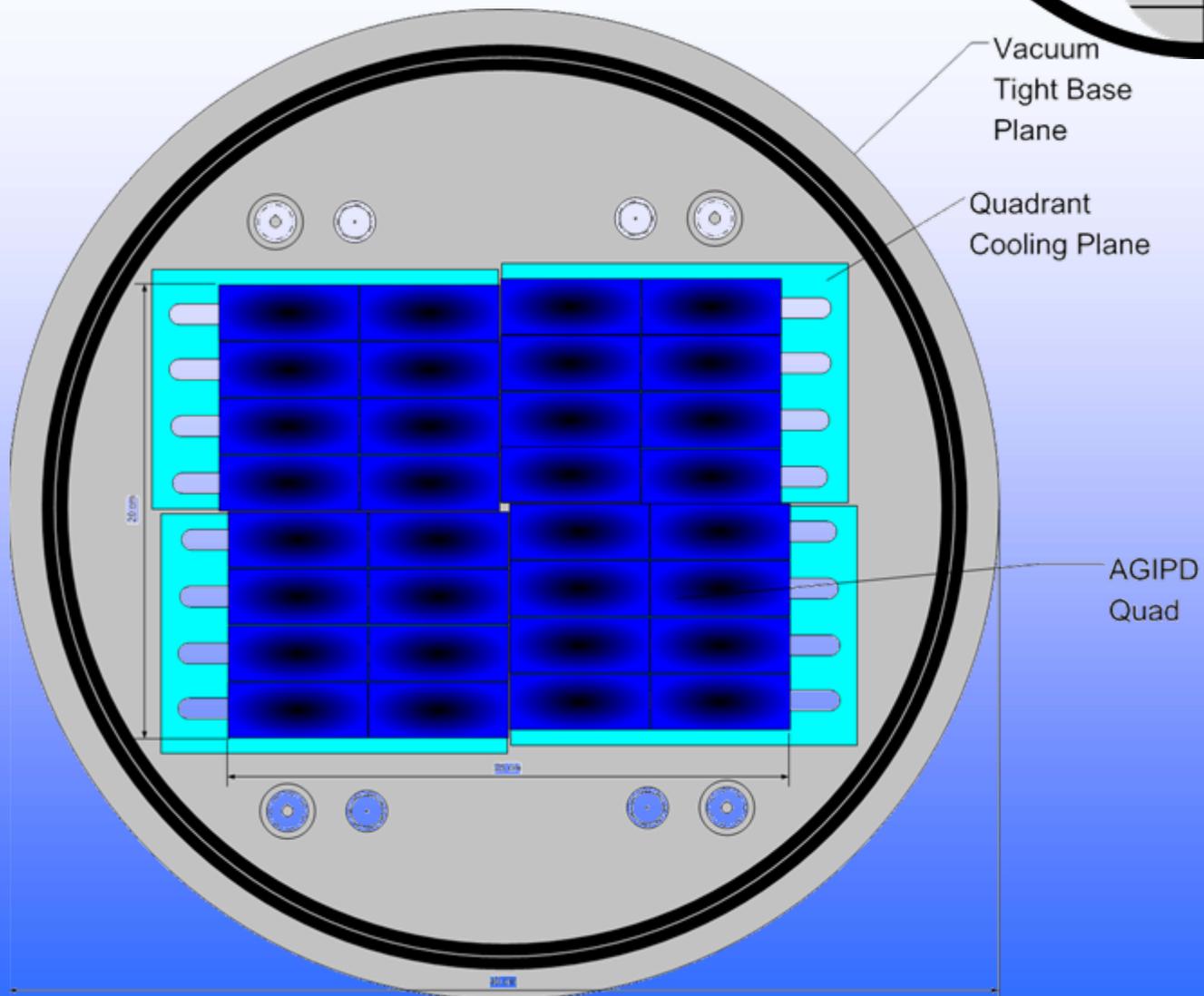


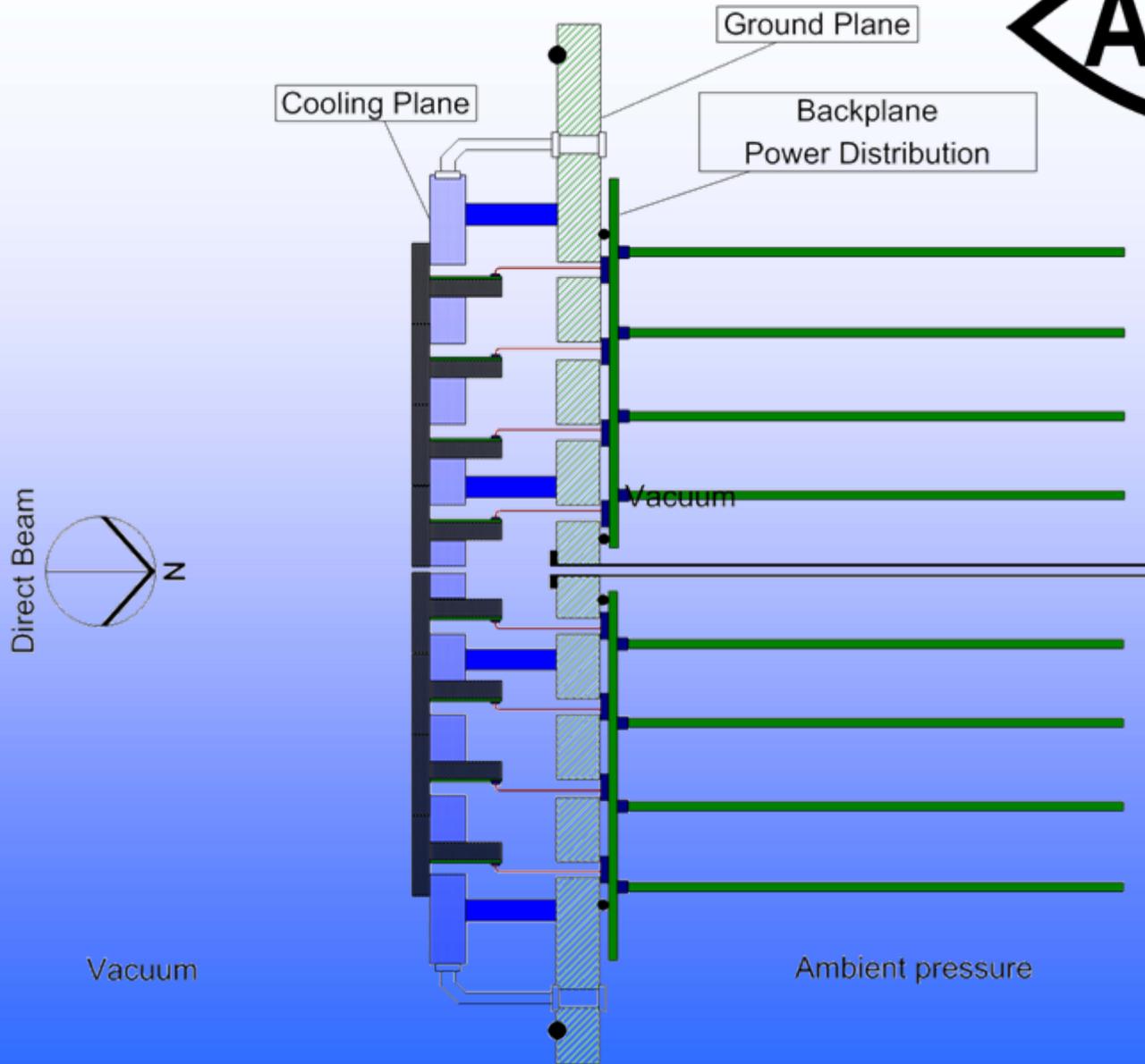
FE Module Design



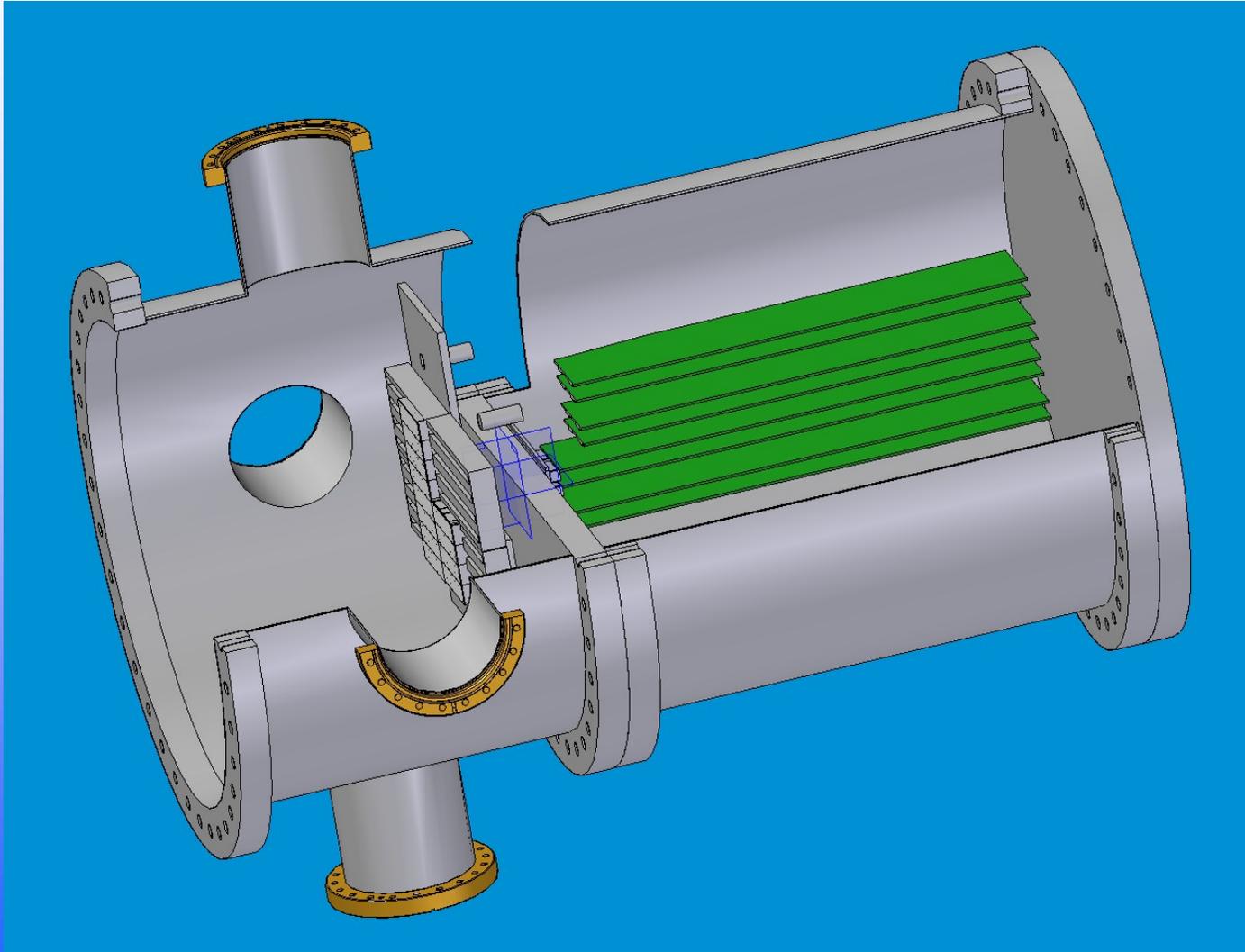
Requirements:

- The mechanics should meet the following requirements:
- Mechanical stability and high precision positioning of the modules.
- Cooling of the chips to -15°C .
- Easy maintenance access and module replacement.
- Operate under ambient pressure or vacuum.
- Support for the front end electronics.





Event



Event



AGIPD Module

Chip Parameters:

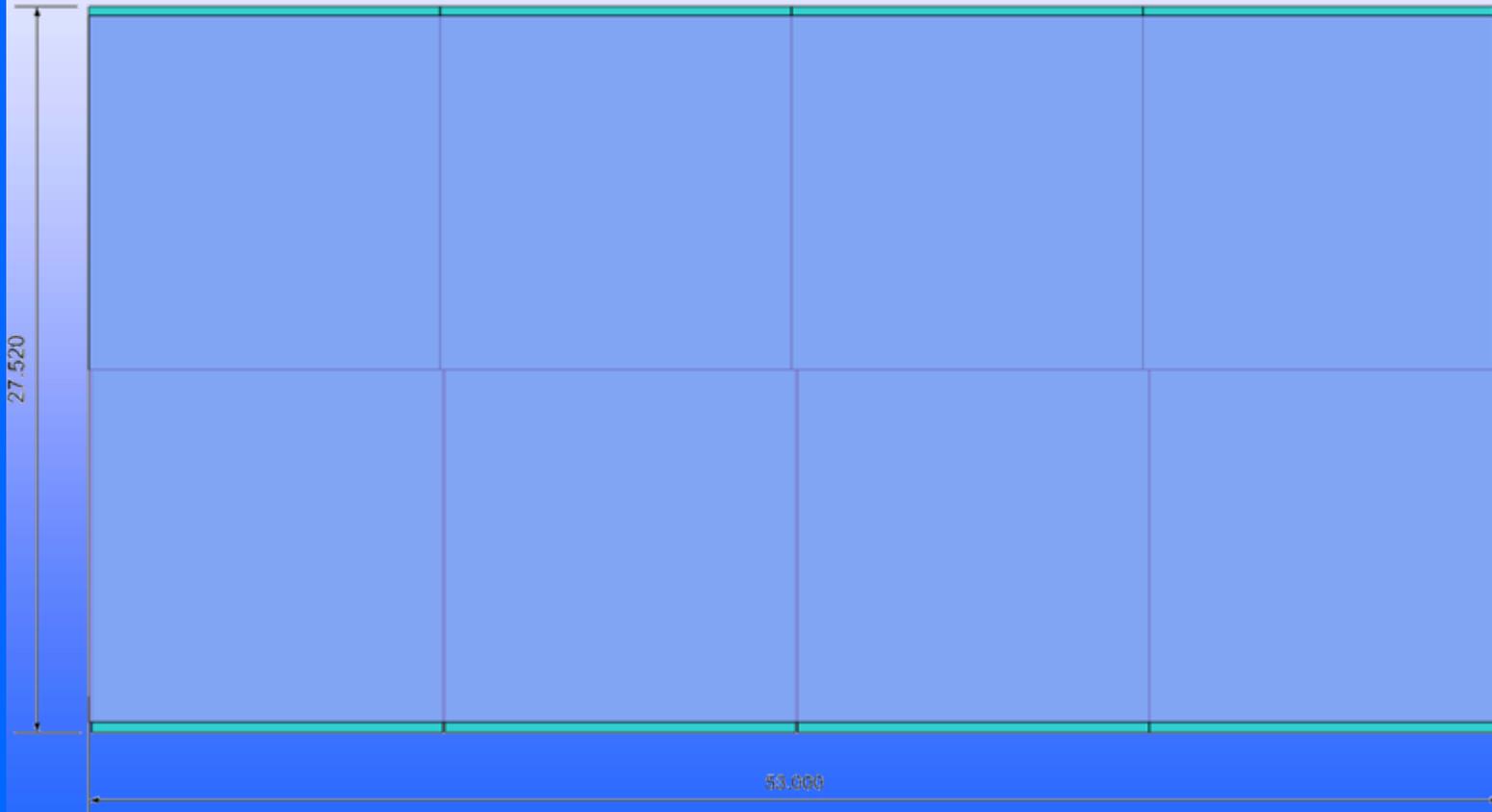
No. of Pixels 64 x 64
Total Area 12.92 x 13.72

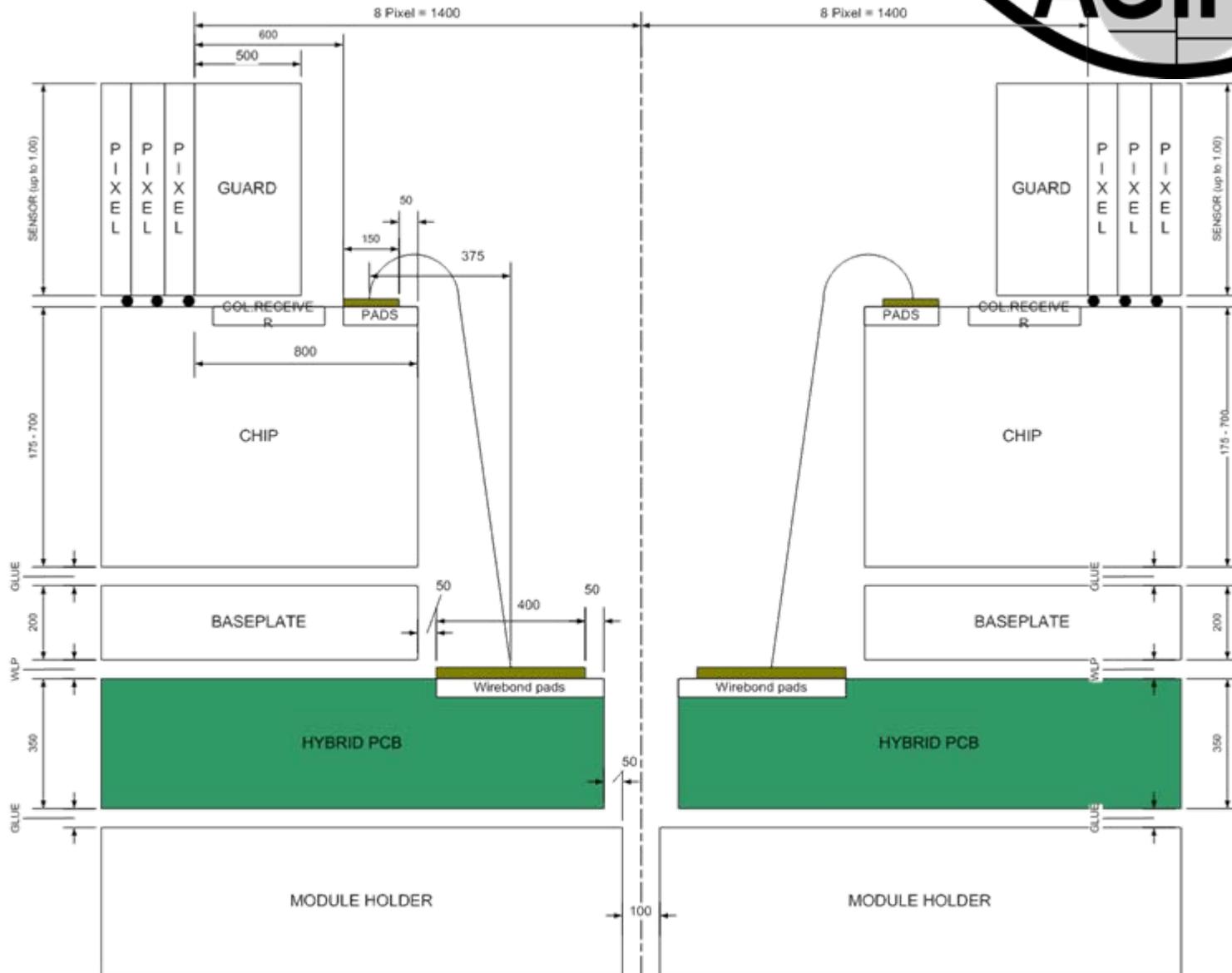
Module Parameters:

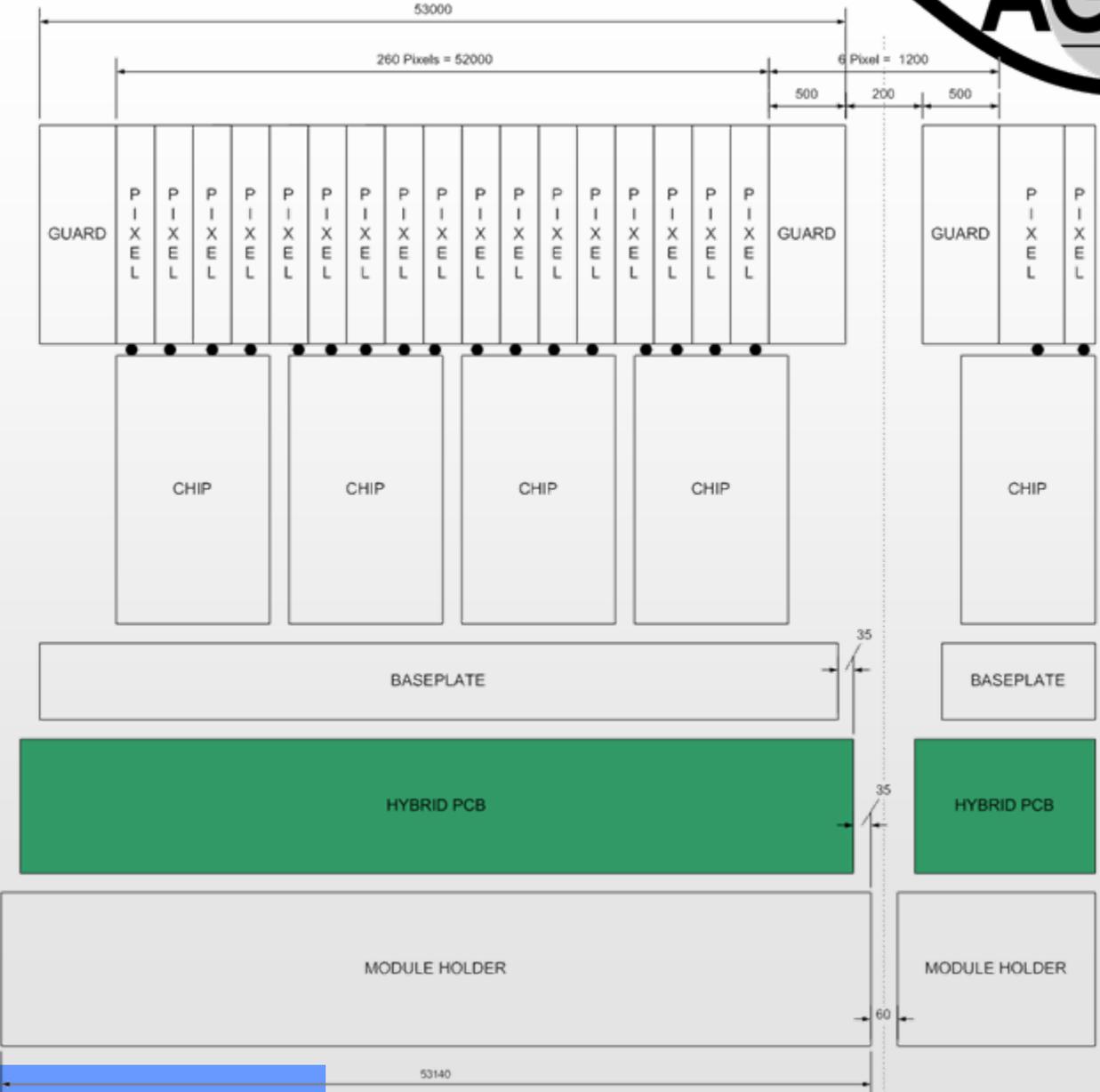
No. of Pixels 259 x 129
Active Area 51.800 x 25.800
Total Area (Sensor) 53.000 x 26.800
Baseplate 53.000 x 27.520
HDI 53.070 x 28.520
Support 53.140 x 28.620

Multi Module Parameters:

No. of dead Gap Pixels (2x3) x (2x8)
No. of Pixels incl. Gap 262 x 137







Event



Komponente des Wärmestroms

Typ: Komponente des Wärmestroms (Z-Achse)

Einheit: W/mm²

Zeit: 1

07.04.2009 18:29

